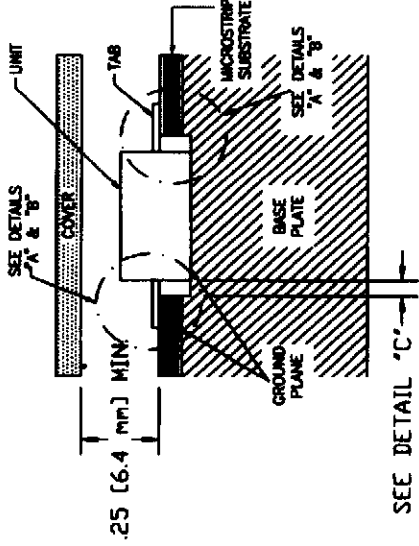
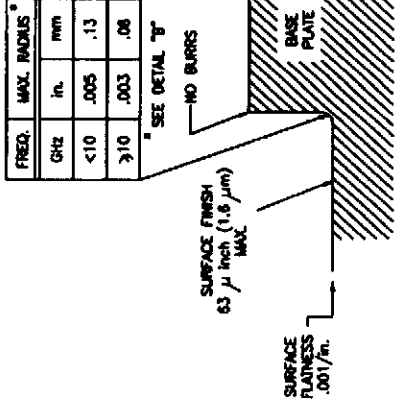


MOUNTING SPECIFICATIONS
FOR DROP-IN DEVICES

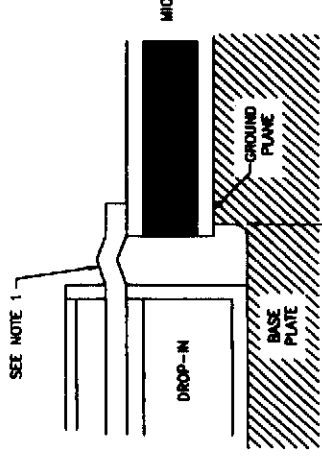


SEE DETAIL 'C'

DETAIL "A"

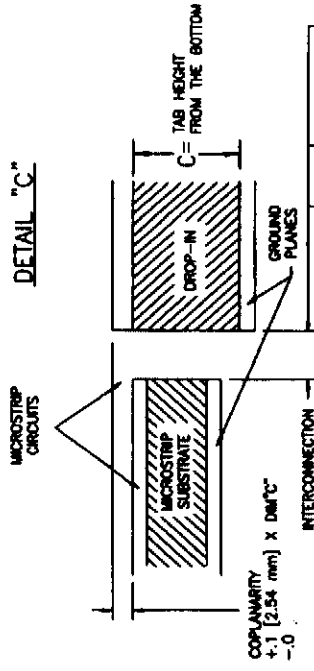


DETAIL "B"



SEE NOTE 3

DETAIL "C"



FREQ.	MAX. GAP
GHz	in. mm
2.5	.010 .25
10	.005 .13
18	.003 .08

NOTES:

1. Tab should be bent slightly to allow for thermal expansion effects.
2. Linear coefficient of thermal expansion for ferrite substrate 8-9 ppm/°C
3. Outer edge of recess may be located slightly underneath MIC substrate to allow for larger corner radius.
4. Following installation options may be considered for best results. REC does not assume any liability for damages caused by our recommendations.
 - If mounting holes are provided, screw unit down using standard screws.
 - Apply silver epoxy evenly at bottom of unit, with out epoxy coming in touch with circuit (avoid shorting). Properly cure under pressure per epoxy manufacturer's instruction.
 - Solder unit to floor using Indalloy #2 solder.
 - Use ABLEFILM 5025E (made by ABLESTICK LABORATORIES, TEL# (213) 764-4600) per manufacturer's instructions (Approved MIL-STD-883B, method 5011)